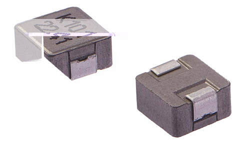
SMD Low Profile High Current Molded Inductor
Size 5030



▪ High performance realized by metal dust core and hot pressing process.
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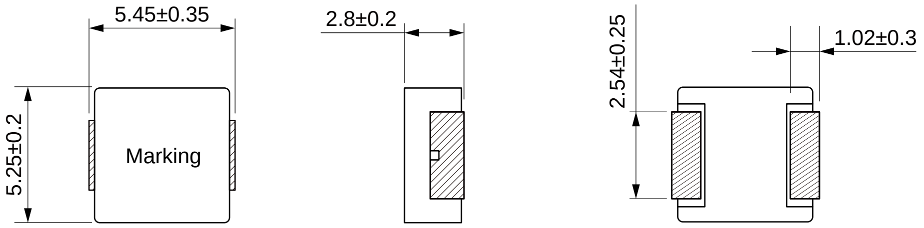
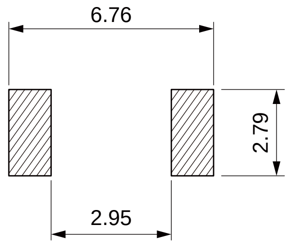
▪ Thermal management products, such as water pumps and valves
▪
▪ HVAC

Dimensions: [mm]



Land Pattern: [mm]

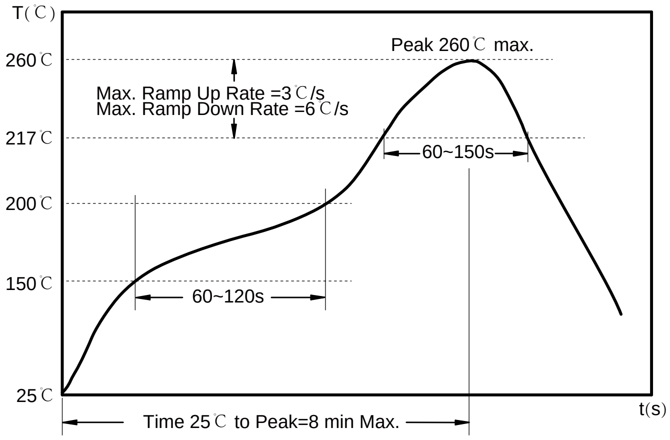


Electrical Properties:

Part No	**Inductance @ 100KHz/1V**	**Tolerance**	**Temperature Rise Current Typ.**	**Temperature Rise Current Max.**	**Current Typ.**	**Current Max.**	**DC Resistance Max.**
MDA5030HT-R33M	0.33	±20%	16.7	15.0	11.2	9.6	5.00
MDA5030HT-R68M	0.68	±20%	11.3	10.2	11.7	10.0	9.74
MDA5030HT-1R0M	1.00	±20%	10.8	9.7	8.0	6.5	11.5
MDA5030HT-1R5M	1.50	±20%	8.2	7.4	7.1	5.9	17.7
MDA5030HT-2R2M	2.20	±20%	7.1	6.4	6.3	5.1	23.0
MDA5030HT-3R3M	3.30	±20%	5.5	5.0	5.5	4.7	38.0
MDA5030HT-4R7M	4.70	±20%	4.4	3.9	4.5	3.9	59.0
MDA5030HT-6R8M	6.80	±20%	3.5	3.1	3.5	3.0	92.0
MDA5030HT-100M	10.0	±20%	2.8	2.5	2.35	2.0	129.5

△

Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

Allowed time above 217℃: 60~150 sec.

Max temperature: 260℃.

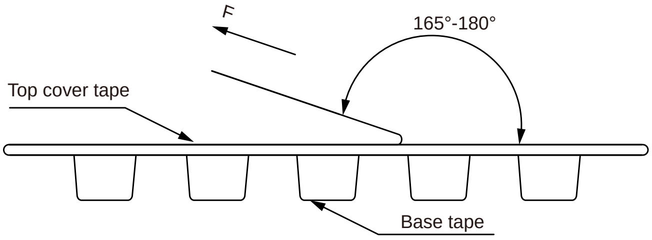
Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension:

Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDA5030HT	5.75±0.1	6.05±0.1	1.5±0.1	4.0±0.1	8.0±0.1	12.0±0.3	3.6±0.1	1.75±0.1	0.35±0.05

Peel force of top cover tape:

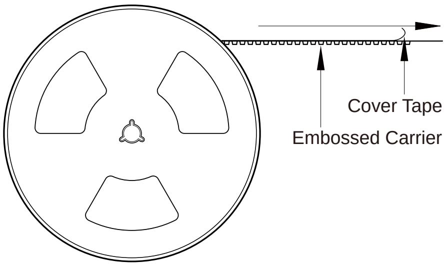


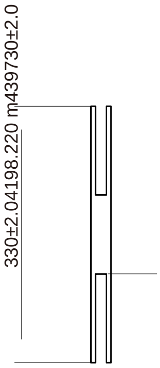
The peel force of top cover tape shall be between 0.1 to 1.3 N

Product Marking:

Marking	K+Printing (Inductance+period)

Reel Dimension：[mm]





Packaging Quantity: